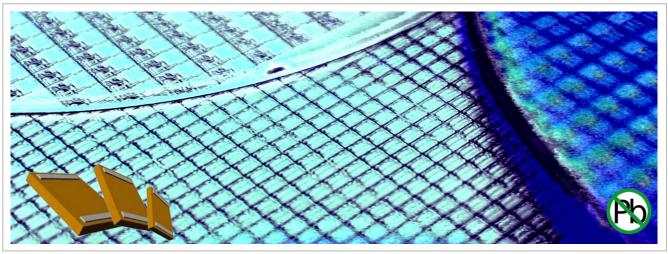


# HSSC426.xxx - 0805 High Stability Silicon Capacitor

**Rev 3.2** 



# **Key features**

- Ultra high stability :
  - **◆** Temperature <±0.5% (-55 °C to +150 °C)
  - Voltage <0.1 %/V</li>
  - Negligible aging <0.001% /1000hours
- Unique high capacitance in EIA/0805 package size, up to 100 nF
- High reliability (FIT <0.017 parts / billion hours)</li>
- Low leakage current down to 100 pA
- Low ESL and Low ESR
- Suitable with lead free reflow-soldering \*Please refer to our assembly Application Note for further recommendations

Thanks to the unique IPDiA Silicon capacitor technology, most of the problems encountered in demanding application can be solved.

High Stability Silicon Capacitors are dedicated to applications where **Reliability** is the main parameter thanks to our end of production Burnin.

HSSC avoid the need to oversize the capacitor value for sensitive capacitive circuitry and offers a higher DC voltage stability.

This technology provides industry leading performances relative to the capacitor stability over the full operating voltage & temperature range.

The very high and stable insulation resistance of silicon capacitors can enhance up to 30 % the **battery lifetime** in mobile applications.

## **Key applications**

- All demanding applications, such as medical, aerospace, automotive industry
- High stability applications
- Decoupling / Filtering / Charge pump (i.e.: Pacemakers / defibrillators)
- Devices with battery operations
- Replacement of X7R and NP0
- Downsizing

The IPDiA technology features a capacitor integration capability (up to 250nF/mm²) which allows a **smaller case size** than existing solutions to answer high volume constraints. This technology also offers **high reliability**, up to 10 times better than alternative capacitor technologies, such as Tantalum or MLCC, and eliminates cracking phenomena.

This Silicon based technology is RoHS compliant and compatible with lead free reflow soldering process.





## **Electrical specification**

		Capacitance value					
		10	15	22	33	47	68
Unit	10 pF	Contact IPDIA Sales	Contact IPDIA Sales	Contact IPDIA Sales	Contact IPDIA Sales	Contact IPDIA Sales	Contact IPDIA Sales
	0.1 nF	Contact IPDIA Sales	Contact IPDIA Sales	Contact IPDIA Sales	Contact IPDIA Sales	Contact IPDIA Sales	Contact IPDIA Sales
	1 nF	10 nF: 935.131.426.510	Contact IPDIA Sales				
	10 nF	100 nF:					

(*) Thinner thickness (as low	as 100 µm thick) available,	see Low Profile Silicon	Capacitor product: LPSC
-------------------------------	-----------------------------	-------------------------	-------------------------

<sup>(\*\*)</sup> Extended temperature range (up to +250 °C) available, see Xtreme Temperature Silicon Capacitor product: XTSC

(\*\*\*) Other values on request.

<u>Parameters</u>	<u>Value</u>		
Capacitance range	10nF to 100 nF <sup>(***)</sup>		
Capacitance tolerances	±15 % <sup>(***)</sup>		
Operating temperature range	-55 °C to 150 °C (**)		
Storage temperatures	- 70 °C to 165 °C		
Temperature coefficient	<±0.5 %, from -55 °C to +150 °C		
Breakdown voltage (BV)	11 VDC <sup>(***)</sup>		
Capacitance variation versus RVDC	0.1 % /V (from 0 V to RVDC)		
Equivalent Serial Inductor (ESL)	Max 250 pH		
Equivalent Serial Resistor (ESR)	$Max 400mΩ^{(***)}$		
Insulation resistance	100G $\Omega$ min @ 3V from -55°C to +,150°C		
Ageing	Negligible, < 0.001 % / 1000 h		
Reliability	FIT<0.017 parts / billion hours,		
Capacitor height	Max 400 μm <sup>(*)</sup>		

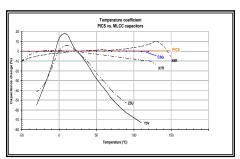


Fig.1 Capacitance change versus temperature variation compared with alternative dielectrics

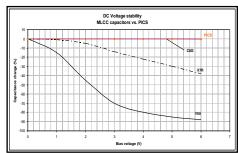


Fig.2 Capacitance change versus voltage variation compared with alternative dielectrics

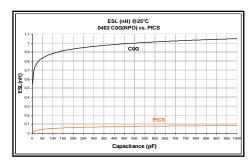
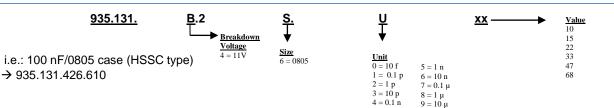


Fig.3 ESL versus capacitance value compared with alternative dielectrics

#### **Part Number**



#### **Termination and Outline**

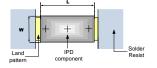
#### **Termination**

Lead-free nickel/solder coating compatible with automatic soldering technologies: reflow and manual.

Typical dimensions, all dimensions in mm.

### Package outline

Тур.		0805	
Comp.	ш	2.16±0.05	
size	W	1.36±0.05	



(0805 PCB footprint)

## **Packaging**

Tape and reel, tray, waffle pack or wafer delivery.

Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner. The information presented in this document does not form part of any quotation or contract, is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent- or other industrial or intellectual property rights.



For more information, please visit: http://www.ipdia.com To contact us, email to: sales@ipdia.com

> Date of release: 28<sup>th</sup> February 2014 Document identifier: CL431 111 615 135